

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

ltc1348csw#pbf

(Engineering Calculation)

SOIC WIDE

(printed on: 2020-07-11 18:49:38)

**TOTAL MASS (g) : 0.752694**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.006857	1000000	9109.93945312		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.185240	975000	246102.546875		
		Iron (Fe)	7439-89-6	0.004560	24000	6058.23583984		
		Phosphorus (P)	7723-14-0	0.000057	300	75.7279510498		
		Zinc (Zn)	7440-66-6	0.000133	700	176.698532104		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.189990</b>	<b>1000000</b>	<b>252413.21875</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.008359	1000000	11105.9160156		
		<b>External Plating Total:</b>				<b>0.008359</b>	<b>1000000</b>	<b>11105.9160156</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.001513	1000000	2010.11193848		
<b>Internal Plating Total:</b>				<b>0.001513</b>	<b>1000000</b>	<b>2010.11193848</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001675	750000	2225.33862305		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000558	250000	741.336730957		
<b>Die Attach Total:</b>				<b>0.002233</b>	<b>1000000</b>	<b>2966.67578125</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.073286	135000	97364.8828125		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.466860	860000	620251.75		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.002714	5000	3605.71313477		
		<b>Encapsulation Total:</b>				<b>0.542860</b>	<b>1000000</b>	<b>721222.3125</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000882	1000000	1171.79040527		
					<b>TOTAL MASS (g) :</b>	<b>0.752694</b>		